IPC  ASSOCIATION CONNI ELECTRONICS INDUS	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier Info	ormation													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2025-06-08				
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-St	tewards	Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com				
uthorized Rep	oresentative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requ	uester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	M	Manufacturing Site		Weight*	UOM	Unit Type
		NTMFD001N03P9 FET 30V 1.2		FET 30V 1.2 mOhr	nOhm PQFN56MP		2025-06-08 PBB		ВВ	121.06451		mg	Each	
	ing Proccess Informa													·
<u> </u>			Cerminal Base Alloy J-STD-020 MSI		_ Rating	Peak Process Body Temperat		•	i i			of Reflow Cyc	eles	
Matte	e Tin (Sn) - annealed	C	CU Alloy	1			260	(	<u> </u>	30	secon	ds 3		
omments														
vel 1 - maximu	um time at peak temperat	ure during sol	dering is 10-3	30 seconds										
or more inform	nation regarding material	composition	please refer t	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaability and the Company's remedies for issues that arise regarding information the Supplier provides in this f											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	19.1	mg	Supplier	Zinc (Zn)	7440-66-6		0.025	mg
			Supplier	Iron (Fe)	7439-89-6		0.458	mg
			Supplier	Copper (Cu)	7440-50-8		18.617	mg
Die	1.6	mg	Supplier	Silicon (Si)	7440-21-3		1.6	mg
Die Attach Solder	1.936	mg	Supplier	Silver (Ag)	7440-22-4		0.0484	mg
			A	Lead (Pb)	7439-92-1	7a	1.7908	mg
			Supplier	Tin (Sn)	7440-31-5		0.0968	mg
Lead Frame	46.396	mg	Supplier	Silver (Ag)	7440-22-4		0.636	mg
			Supplier	Zinc (Zn)	7440-66-6		0.06	mg
			Supplier	Iron (Fe)	7439-89-6		1.1	mg
			Supplier	Copper (Cu)	7440-50-8		44.6	mg
Mold Compound-Black	43.59	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.18	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.1	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.31	mg
Plating	8.33	mg	Supplier	Tin (Sn)	7440-31-5		8.33	mg
Wire Bond	0.112517	mg	Supplier	Palladium (Pd)	7440-05-3		0.0023	mg
			Supplier	Gold (Au)	7440-57-5		0.0006	mg
			Supplier	Copper (Cu)	7440-50-8		0.1097	mg